

WHAT IS CLAIMED IS:

1. A multilayered circuit board in which interlayer connection is achieved by the contact of minute pointed protrusions, provided on a first conductive circuit layer, with a second conductive circuit layer, wherein

interlayer insulation is achieved by a film having a three-layer structure, comprising a thermoplastic film inserted between a pair of thermosetting adhesive layers.

2. The multilayered circuit board as described in Claim 1, wherein the film having a three-layer structure is characterized in that the thickness of the thermosetting adhesive layers is greater than the thickness of the opposing conductive layers, and the thickness of the thermoplastic film is less than 25 μm .

3. The multilayered circuit board as described in Claim 1, wherein the film having a three-layer structure is characterized in that at least one of the thermosetting adhesive layer and the thermoplastic film is partially cut away.